SPECIFICATIONS CUSTOMER: SAMPLE CODE: RC2004WRF-AWB-B (This Code will be changed while mass production) MASS PRODUCTION CODE: Customer Approved Date:

Sales Sign	QC Confirmed	Checked By	Designer

Approval For Specifications Only.

Approval For Specifications and Sample.

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(PS0405105) NO.PT-A-005-4

^{*} This specification is subject to change without notice.



RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2004/09/20		NEW SAMPLE		



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Note: For detailed information please refer to IC data sheet: <u>ST7066U,KS0063B</u>



1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	20 *4 Characters
LCD Type	FSTN, Transflective, Positive, Normal Temp.
Driver Condition	1/16 Duty , 1/4Bias
Viewing Direction	6 O'clock
Backlight	white LED B/L
Weight	70.0g
Interface	_
Other	

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	98.0 (L) * 60.0 (w) *14.0 (H)(Max)	mm
Viewing Area	76.0 (L) * 25.2 (w)	mm
Active Area	70.4 (L) *20.8 (w)	mm
Dot Size	0.55 (L) * 0.55 (w)	mm
Dot Pitch	0.60(L) * 0.60(w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V_{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V_{LCD}	_	VDD-10.0	V _{DD} +0.3	V
Input Voltage	V _{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T_{OP}	Excluded B/L	0	50	$^{\circ}\mathbb{C}$
Storage Temperature	T_{ST}	Excluded B/L	-20	70	$^{\circ}\!\mathbb{C}$
Storage Humidity	H_D	Ta<40 ℃	-	90	%RH



1.4 DC Electrical Characteristics

 $V_{DD}\!=5.0~V\pm10\%$, $V_{SS}\!=0V$, $Ta=25\,^{\circ}\!\text{C}$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V_{DD}	_	4.5	5.0	5.5	V
"H" Input Voltage	V _{IH}	_	$0.7V_{DD}$	-	V_{DD}	V
"L" Input Voltage	V _{IL}	_	-0.3	-	0.6	V
"H" Output Voltage	V _{OH}	IOH=-0.1mA	3.9	-	V_{DD}	V
"L" Output Voltage	V _{OL}	IOL=0.1mA	-	-	0.4	V
Supply Current	I _{DD}	V _{DD} = 5.0 V	0.8	1.38	1.5	mA
		0°C	4.7	4.8	4.9	
LCM Driver Voltage	V _{OP}	25°C *1	4.6	4.7	4.9	V
		5 0°C	4.3	4.5	4.6	

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - V_{O}

1.5 Optical Characteristics

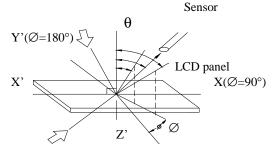
1/16Duty , 1/4Bias , VLCD = 4.6V , Ta = 25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	C <u>≥</u> 2.0,∅= 0°	40°	-	-	Notes 1 & 2
Contrast Ratio	С	θ=25°, Ø= 0°	6	8	-	Note 3
Response Time(rise)	tr	θ= 25°, Ø= 0°	-	70 ms	105 ms	Note 4
Response Time(fall)	tf	θ= 25°, Ø= 0°	-	150ms	225 ms	Note 4



Note 1: Definition of angles θ and \emptyset

Light (when reflected) $z (\theta=0^{\circ})$

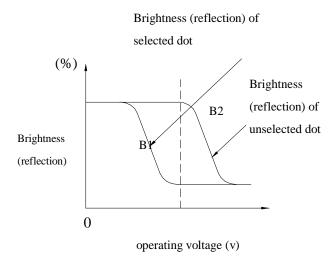


Light (when transmitted) $Y(\varnothing=0^{\circ})$ $(\theta=90^{\circ})$

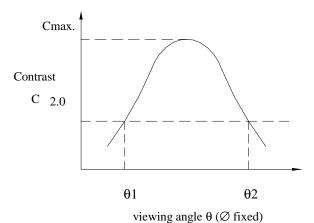
Note 3: Definition of contrast C

Brightness (reflection) of unselected dot (B2)

Brightness (reflection) of selected dot (B1)

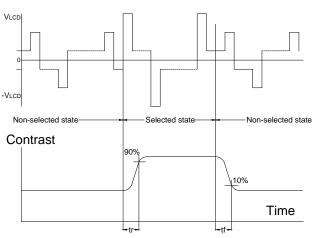


Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$



Note : Optimum viewing angle with the $naked\ eye\ and\ viewing\ angle\ \theta\ at$ $Cmax.\ Above\ are\ not\ always\ the\ same$

Note 4: Definition of response time



Note: Measured with a transmissive LCD panel which is displayed 1 cm²

 V_{LCD} : Operating voltage f_{FRM} : Frame frequency t_r : Response time (rise) t_f : Response time (fall)



1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	-	72	mA
Reverse Voltage	VR	Ta =25°C	-	5	V
Power Dissipation	PO	Ta =25°℃	-	0.29	W
Operating Temperature	T _{OP}	-	-20	70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-	-30	80	$^{\circ}\! \mathbb{C}$
Solder Temp. for 3 Second	-	-	-	260	$^{\circ}\!\mathbb{C}$

Electrical / Optical Characteristics

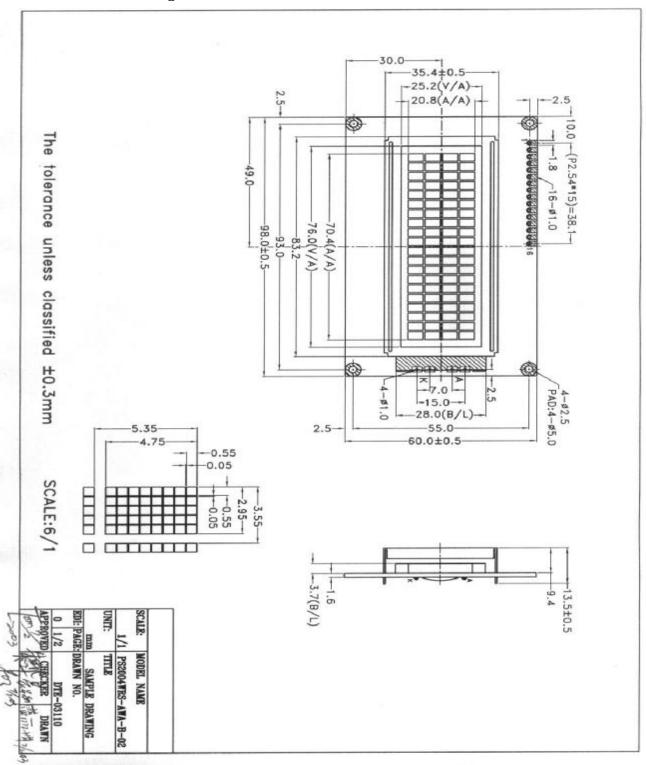
Ta =25°C

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=60 mA	3	3.3	4	V
Reverse Current	IR	VR=5V	-	-	0.15	mA
Average Brightness (with LCD)	IV	IF=60 mA	-	-	-	cd/m ²
Wavelength	λр	IF=60 mA	-	-	-	nm
Luminous Intensity (without LCD)	IV	IF=60 mA	185	290		cd/m ²
Color			White			

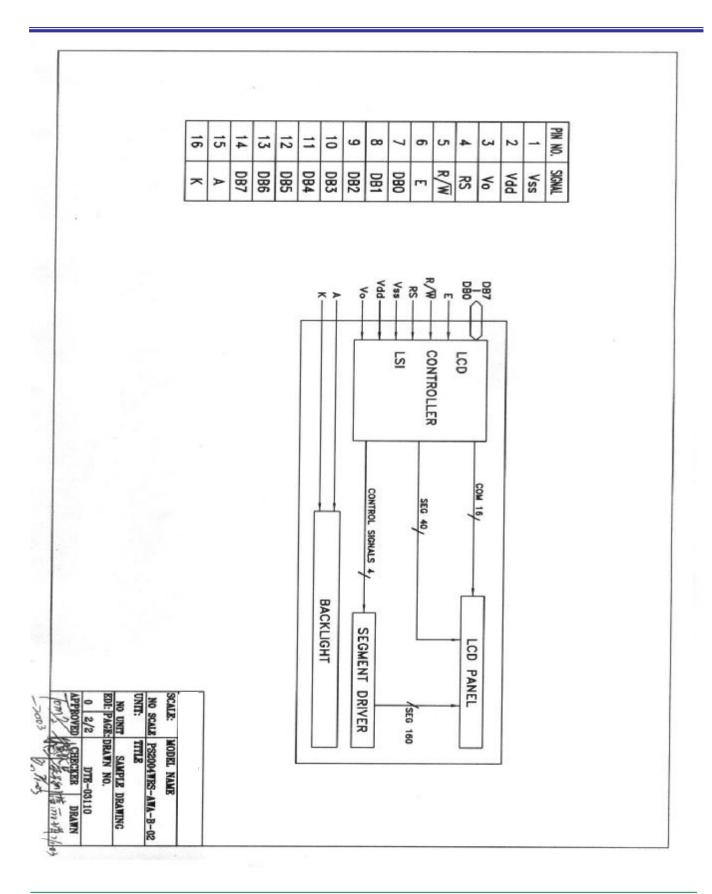


2. MODULE STRUCTURE

2.1 Counter Drawing





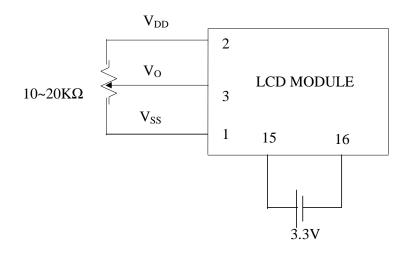




2.2 Interface Pin Description

Pin No.	Symbol	Signal Description
1	Vss	Power Supply (V _{SS} =0)
2	Vdd	Power Supply (V _{DD} >V _{SS})
3	Vo	Operating voltage for LCD (variable)
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
		Read/Write signal input is used to select the read/write
5	R/\overline{W}	mode.
		High = Read mode, Low = Write mode
6	E	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines.
7~10	DB0 ~ DB3	Used for data transfer between the MPU and the LCD
/~10	DB0 ~ DB3	module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4 ~ DB7	Used for data transfer between the MPU and the LCD
		module.
		DB7 can be used as a busy flag.
15	A	Power supply for LED B / L (+)
16	K	Power supply for LED B / L (-)

Contrast Adjust

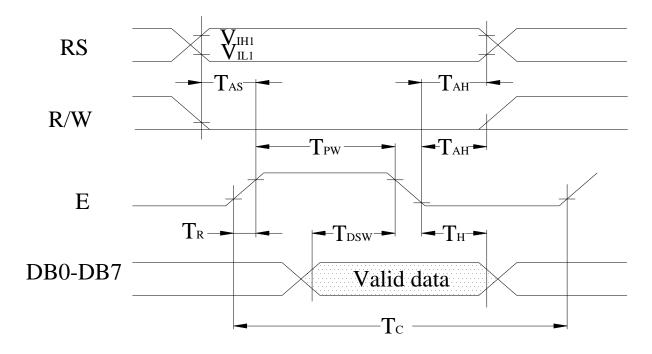


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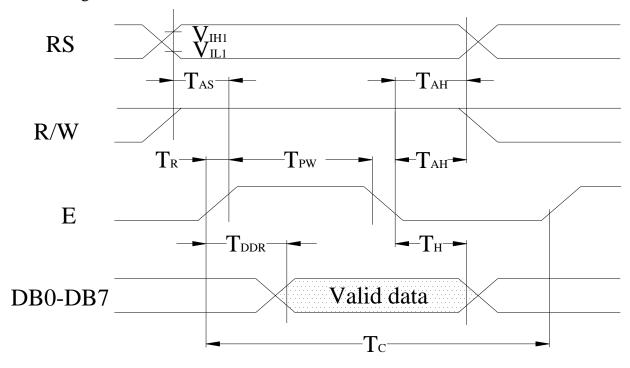


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



I Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

 $(\text{Vcc} = +5\text{V}, \text{Ta} = 25^{\circ}\text{C})$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R , T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T_{AS}	Address Setup Time	Pins: RS , RW,E	0	ı	ı	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	1	1	ns
T_{DSW}	Data Setup Time	Pins:DB0~DB7	40	-	-	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Read Mode (Reading data from ST7066U to MPU)

 $(Vcc = +5V,Ta=25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	1	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R , T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T_{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns



2.4 Display Command

	Instruction Code								Description			
Instructions	RS	R/W	DB 7	DB 6	DB 5	DB 4	DB 3	DB 2	DB 1	DB 0	Description	Time (270KHz)
			,	0			3	2	1	U	Write "20H" to DDRAM, and set	
Clear	0	0	0	0	0	0	0	0	0	1	DDRAM address to "00H" from	1.52ms
Display	U	U	U	U	U	U	0	U	U	1	AC.	1.321118
											Set DDRAM address to "00H"	
D .											from AC and return cursor to it's	
Return	0	0	0	0	0	0	0	0	1	×	original position if shifted.	1.52ms
Home											The contents of DDRAM are not	
											changed.	
											Sets cursor move direction and	
Entry Mode					0	0			T/D		specifies display shift. These	25
Set	0	0	0	0	0	0	0	1	I/D	S	operations are performed during	37µs
											data write and read .	
Display											D=1 : entire display on	
ON/OFF	0	0	0	0	0	0	1	D	C	В	C=1 : cursor on	37µs
											B=1 : cursor position on	
											Set cursor moving and display	
Cursor or	0	0	0	0	0	1	G/G	ъ/г			shift control bit, and the direction,	27
Display	0	0	0	0	0	1	S/C	R/L	×	×	without changing of DDRAM	37µs
Shift											data.	
F4:											DL: interface data is 8/4 bits	
Function	0	0	0	0	1	DL	N	F	×	×	NL: number of line is 2/1	37µs
Set											F: font size is $5 \times 11/5 \times 8$	
Set					10	10	10	10	40	40	Sat CCD AM address in address	
CGRAM	0	0	0	1	AC 5	AC 4	AC 3	AC	AC		Set CGRAM address in address	37µs
Address					3	4	3	2	1	0	counter.	
Set				AC	AC	AC	AC	AC	AC	AC	Set DDRAM address in address	
DDRAM	0	0	1	6	5 5	4	3	$\frac{AC}{2}$	1	0	counter.	37µs
Address				U	3	+	3		1	J	counter.	



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μs
Write Data	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM	37µs
to RAM											(DDRAM/CGRAM).	·
Read Data	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM	37µs
from RAM	1	1	יט	סם	D3	D4	D3	DZ	Di	DU	(DDRAM/CGRAM).	37μ8

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Refer to Instruction Table for the list of each instruction execution time.



2.5 Character Pattern

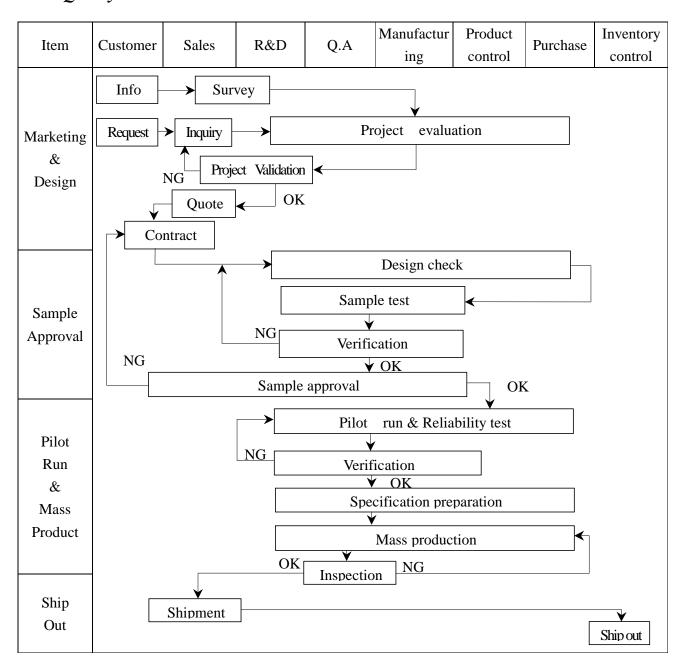
■ CHARACTER PATTERN(EB,WB)

		H	ligh	4-b	it (D	4to	D7	of (Cha	ract	erC	ode	(H	exa	deci	mal)
		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F
	0	CG RAM (1)	::::				<u> </u>	=:	ļ:::-	-		-==	-	l'			TT.
	1	CG RAM (2)	===	1	1.		(3)	-===	-::4		-111	i		.]		`;·	-
	2	CG RAM (3)	" ."	::	2			E	ļ		H	÷	-:-	-00	:::::	::::	
,	3	CG RAM (4)		##			5	: <u></u> .	::::-	-#	::::	ú	•-	[[::::	4]]	===	
5	4	CG RAM (5)	15-	:	::].		-T-		╬	- 🔠	-::-				I		())
2000	5	CG RAM (6)	I.	: ::::		E	II	====	II	-	<u>:::</u> :	£	1:2	-†-	æi	1"	-
	6	CG RAM (7)		8.	:		I.,.I	₽,	۱.,.۱	-∰			I _{I.[}				!
4-bit (D0 to D3) of Character Code (Hexadecimal)	7	CG RAM (8)	_=	:=		Œ	إبرا		1,.,1	===		Fi.	; =:		: ¹ :	Ĭ	==
	8	CG RAM (1)		C			: <:	-	;×:;		Ċ.	.#		- <u>:</u>	Ξ	H	
	9	CG RAM (2)			9	I	٠,	i	·:::I	::::	-	:	≦	I	III	<i>3</i> .	
	Α	CG RAM (3)	\approx	:4:	#	J.	Z	.j	:						Œ	 l.	
Lower	В	CG RAM (4)	!"		#	K		le:	-{[1	Fi	3	-:::[L	1	1,.29	
	С	CG RAM (5)	:::::	:=	<.	<u></u>	٠.,	1	i	î	P	8]:::-		•	4	
	D	CG RAM (6)	··.					m]-	ì.	:::::		:::::::::::::::::::::::::::::::::::::::	==		M	
	E	CG RAM (7)	iii	::	\geq	 	٠٠٠.	-"	٠٠.	Ä							
	F	CG RAM (8)	∄		7				d.	ıä,	ċ.	ggi			C)(



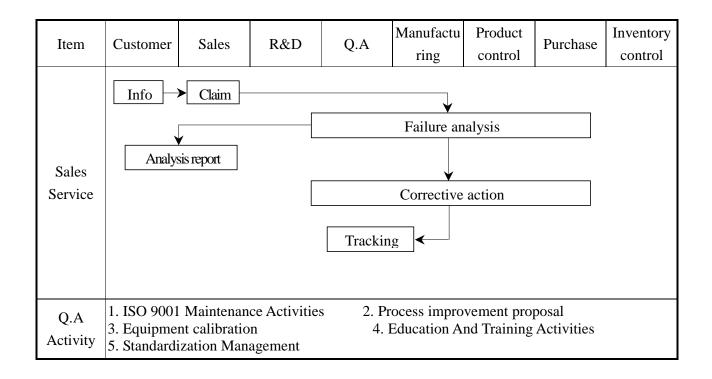
3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart



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3.2 Inspection Specification

Equipment: Gauge · MIL-STD · Powertip Tester · Sample ·

IQC Defect Level : Major Defect AQL 0.4; Minor Defect AQL 1.5 $\,^{\circ}$

FQC Defect Level: 100% Inspection • OUT Going Defect Level: Sampling •

Specification:

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of	Missing line.	N.G.	Major
3	LCM	The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major
	$A=(L+W)\div 2$	There is no function.	N.G.	Major
		Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is > 0.4 mm	N.G.	Minor
	$\begin{array}{c} LCD \\ A=(L+W) \div 2 \end{array}$	Dirty particle length is $>$ 3.0mm, and 0.01mm $<$ width \leq 0.05mm	N.G.	Minor
4	Dirty particle (Including scratch · bubble)	Display is without protective film	N.G.	Minor
		Conductive rubber is over bezel 1mm	N.G.	Minor
		Polarizer exceeds over viewing area of LCD	N.G.	Minor
		Area of bubble in polarizer, $A > 1.0$ mm, the number of bubble is > 1 piece.	N.G.	Minor
		0.4mm $<$ Area of bubble in polarizer, A $<$ 1.0 mm, the number of bubble is $>$ 4 pieces.	N.G.	Minor
		Burned area or wrong part number is on PCB	N.G.	Major
		The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor
		The stripped solder mask, A is > 1.0mm	N.G.	Minor
	Appearance of	0.3mm < stripped solder mask or visible circuit, A < 1.0mm, and the number is ≥4 pieces	N.G.	Minor
5	PCB	There is particle between the circuits in solder mask	N.G	Minor
	$A=(L+W)\div 2$	The circuit is peeled off or cracked	N.G	Minor
		There is any circuits risen or exposed.	N.G	Minor
		$0.2 \text{mm} < \text{Area of solder ball, A is } \leq 0.4 \text{mm}$ The number of solder ball is ≥ 3 pieces	N.G	Minor
		The magnitude of solder ball, A is >0.4mm.	N.G	Minor



NO	Item	Specification	Judge	Level
		The shape of modeling is deformed by touching.	N.G.	Major
	Appearance of	Insufficient epoxy: Circuit or pad of IC is visible	N.G.	Minor
6	molding A=(L+W)÷2	Excessive epoxy: Diameter of modeling is >20mm or height is >2.5mm	N.G.	Minor
		The diameter of pinhole in modeling, A is > 0.2 mm.	N.G.	Minor
		The folding angle of frame must be $>45^{\circ} +10^{\circ}$	N.G.	Minor
7	Appearance of frame	The area of stripped electroplate in top-view of frame, A is >1.0mm.	N.G.	Minor
/	$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
		The scratched width of frame is >0.06mm. (Top view only)	N.G.	Minor
	Electrical	The color of backlight is nonconforming	N.G.	Major
	Electrical characteristic of	Backlight can't work normally.	N.G.	Major
8	backlight	The LED lamp can't work normally	N.G.	Major
		The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
	$A=(L+W)\div 2$	The height of solder pin for backlight is >2.0mm	N.G.	Minor
		The mark or polarity of component is unidentifiable.	N.G.	Minor
		The height between bottom of component and surface of the PCB is floating >0.7mm	N.G.	Minor
10	Assembly parts A=(L + W)÷2	D>1/4W W D D D Pad	N.G.	Minor
	71-(E W): 2	End solder joint width, D' is >50% width of component termination or width of pad	N.G.	Minor
		Side overhang, D is >25% width of component termination.	N.G.	Minor
		Component is cracked, deformed, and burned, etc.	N.G.	Minor
		The polarity of component is placed in inverse direction.	N.G.	Minor
		Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5mm.	N.G.	Minor
		I	_1	1



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Co	ondition					
1	High Temperature Storage	Storage at 80 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
2	Low Temperature Storage	Storage at -30 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition 4hrs						
3	High Temperature /Humidity Storage	1.Storage 96~100 hrs 60±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer). or 2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding temperature, then storage at normal condition 4 hrs.						
4	Temperature Cycling	$-20^{\circ}\text{C} \rightarrow 25^{\circ}\text{C} \rightarrow 70^{\circ}\text{C} \rightarrow 25^{\circ}\text{C}$ $(30\text{mins}) (5\text{mins}) (30\text{mins}) (5\text{mins})$ 10 Cycle						
5	Vibration	10~55Hz (1 minute) 1.5mm X,Y and Z direction * (each 2hrs)						
6	ESD Test	Air Discharge: Apply 6 KV with 5 times discharge for each polarity +/- Testing location: Around the face of LCD	Contact Discharge: Apply 250V with 5 times discharge for each polarity +/- Testing location: 1.Apply to bezel. 2.Apply to Vdd, Vss.					
7	Drop Test	Packing Weight (Kg) 0 ~ 45.4 45.4 ~ 90.8 90.8 ~ 454 Over 454	Drop Height (cm) 122 76 61 46					



5. PRECAUTION RELATING PRODUCT HANDLING 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $280\pm10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.